

PRODUCTION METHOD FOR COPPER-CLAD LAMINATE PLATE

ABSTRACT

5 There is provided a method of producing a copper clad laminate having a copper foil
and a resin bonded at high adhesive force despite the use of a thermoplastic resin
having a low dielectric constant. This method includes the steps of: providing a
roughened copper foil having at least one roughened surface having fine irregularities
composed of acicular crystals containing cupric oxide and cuprous oxide; and bonding
10 a sheet-shaped thermoplastic resin to the roughened surface of the roughened
copper foil to provide a copper clad laminate. The roughened surface has a cupric
oxide thickness of 1 to 20 nm and a cuprous oxide thickness of 15 to 70 nm, both
determined by sequential electrochemical reduction analysis (SERA) at the time of
bonding the thermoplastic resin.

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No Figure